L Number Hits Search Text		DB	Time stamp	
1 5198 (leadframe 1	ead) and (flipchip (flip adj	USPAT;	2003/06/04	13.03
chip))	- and (lipenip (lip dd)	EPO; JPO	2003/06/04	13:03
2 1167 ((leadframe	lead) and (flipchip (flip adj ((encapsulant encapsulated	USPAT;	2003/06/04	13:06
encapsulatin	g sealing sealed molding	EFO, OFO		
molded) with	(polymer polymeric polyimide	1		
plastic))	Wester bordwers bordwing			
3 921 ((leadframe	lead) and (flipchip (flip adj	USPAT;	2003/06/04	12.16
chip))) and	((encapsulant encapsulated	EPO; JPO	2003/00/04	13:13
encapsulatin	g sealing sealed molding	220, 010		
molded) near	3 (polymer polymeric polyimide	i i		
(plastic))				
4 198 (((leadframe	lead) and (flipchip (flip adj	USPAT;	2003/06/04	13.15
(chip))) and	((encapsulant encapsulated	US-PGPUB;		10.10
encapsulating	g sealing sealed molding	JPO;		
molded) near	(polymer polymeric polyimide	DERWENT		
plastic))) an	nd (underfill\$2 (under adj			
5 fill\$2)) 5 278 ((leadframe)		i		
- v ((- coarrame :	ead) and (flipchip (flip adj	USPAT;	2003/06/04	13:15
encansulating	sealing sealed molding	EPO; JPO		
molded) near	(polymer polymeric			
polyimide))	(polymer polymeric		İ	
	lead) and (flipchip (flip adj	USPAT;	2003/06/04	14.01
chip))) and	(encapsulant encapsulated	US-PGPUB;	2003/06/04	14:21
encapsulating	scaling sealed molding	JPO;		1
molded) near:	(polymer polymeric	DERWENT		
polyimide)))	and (underfill\$2 (under adj			
fill\$2))	_	Í		İ
7 31 ((((leadframe	lead) and (flipchip (flip	USPAT;	2003/06/04	15:16
adj chip))) a	nd ((encapsulant encapsulated	US-PGPUB;		İ
encapsulating	sealing sealed molding	JPO;		
molded) nears	(polymer polymeric	DERWENT		,
	and (underfill\$2 (under adj			
8 100 (((leadframe	lead) and (flipchip (flip adj	USPAT;	2002/06/04	15 16
(chip))) and ((encapsulant encapsulated	US-PGPUB;	2003/06/04	12:10
encapsulating	sealing scaled molding	JPO;		
molded) near3	(polymer polymeric	DERWENT		j
polyimide)))	and pitch			
9 69 ((((leadframe	lead) and (flipchip (flip	USPAT;	2003/06/04	15:16
adj chip))) a	nd ((encapsulant encapsulated	US-PGPUB;		
encapsulating	sealing scaled molding	JPO;		
molded) near3	(polymer polymeric	DERWENT		
polyimide)))	and pitch) not ((((leadframe			
read) and (11	ipchip (flip adj chip))) and			
(tencapsurant	encapsulated encapsulating d molding molded) near3			}
(polymer poly	meric polyimide))) and			İ
(underfills2	(under adj fill\$2))) and			
pitch)	(aa aa) 1.1142/// and			
10	lead) and (flipchip (flip adj	USPAT;	2003/06/04	15.17
chip))) and ((encapsulant encapsulated	US-PGPUB;	_000,00,04	-3.1
encapsulating	sealing sealed molding	JPO;		
molded) near3	(polymer polymeric	DERWENT		
[polyimide))	and (lead near3 pitch)			

L Number	Hits	Search Text	DB	Time at a man
41	17	("3691289" "3765590" "4109096"	USPAT	Time stamp 2003/06/05 09:15
1		"4183135" "4312926" "4657170"	OBIAI	2003/00/03 09:15
1		"4999699" "5034349" "5080279"	i	
l	}	"5146310" "5289344" "6034422"		i l
į l		"6160312" "6184573" "6191952"		
		"6232148" "6258622").PN.		i
42	1	6160312.URPN.	USPAT	2003/06/05 09:17
45	15	("4774630" "5222014" "5237434"	USPAT	2003/06/05 09:17
}		"5266912" "5454160" "5491612"		2003/00/03 03:1/
		"5559305" "5565706" "5568574"		1
		"5652462" "5677567" "5801433"		,
7.0		"5869895" "5907166" "6043557").PN.		
70	13	6140144.URPN.	USPAT	2003/06/05 09:22
71	13	6140144.URPN.	USPAT	2003/06/05 09:23
72	10	("4763098" "4838089" "5209122"	USPAT	2003/06/05 09:24
j	i	"5285690" "5591679" "5600071"	i	
		"5646072" ! "5721446" "5889211"		
73	7.5	"5994161").PN.		
74	15	6108210.URPN.	USPAT	2003/06/05 09:24
' '	5	("5528083" "5801447" "6108210"	USPAT	2003/06/05 09:25
77	ا ه	"6121690" "6365436").PN.		
108	10	6462427.URPN.	USPAT	2003/06/05 09:26
109	10	5895229.URPN.	USPAT	2003/06/05 09:31
110	10	5895229.URPN.	USPAT	2003/06/05 09:32
	′ [("5089440" "5218759" "5285352"	USPAT	2003/06/05 09:32
		"5302849" "5371404" "5682066" "5804881").PN.	1	i
				

L Numbe	r Hits	Search Text	DB	T T :
1				Time stamp
	1	*	USPAT;	2003/06/04 09:12
	1		US-PGPUB; EPO; JPO;	
1.	1		DERWEN'T	
2	2.	5450283.pn.	USPAT;	2003/06/04 09:12
			US-PGPUB:	2003/06/04 09:12
			EPO; JPO;	ĺ
			DERWENT	}
3	2.	5784261.pn.	USPAT;	2003/06/04 09:12
ļ			US-PGPUB;	
			EPO; JPO;	İ
		500000	DERWENT	
4	2	5895229.pn.	USPAT;	2003/06/04 09:13
İ			US-PGPUB;	
ļ			EPO; JPO;	
5	_	5001214	DERWENT	
1.	2.	5981314.pn.	USPAT;	2003/06/04 09:13
			US-PGPUB;	
-	1		EPO; JPO;	
6	2	 5000242 mm	DERWENT	
ĺ	1	5998243.pn.	USPAT;	2003/06/04 09:16
			US-PGPUB;	
			EPO; JPO;	1
17	2	6038136.pn.	DERWENT	
1	1	0030130.pm.	USPAT;	2003/06/04 09:17
			US-PGPUB;	
			EPO; JPO;	
8	2	6049122.pr.	DERWENT	Í
	[USPAT;	2003/06/04 09:17
	i 1		US-PGPUB;	į
			EPO; JPO;	
9	2	6071755.pn.	DERWENT	2002/06/5
1	-	· F	USPAT;	2003/06/04 09:17
]		US-PGPUB; EPO; JPO;	
1	[DERWENT	1
10	2	6081997.pn.	USPAT;	2003/06/04 09:17
!		•	US-PGPUB;	2003/06/04 09:1/
	1		EPO; JPO;	
ĺ			DERWENT	
11.	2 [6344162.pn.	USPAT;	2003/06/04 09:17
	1		US-PGPUB;	2003/00/04 09:1/
!			EPO; JPO;	
10	1 . 1		DERWENT	
12	0	us20020109241	USPAT;	2003/06/04 09:18
1			US-PGPUB;	,,,,,,,,,,
ļ			EPO; JPO;	
13		H00000100011	DERWENT	j
1 13	2	"20020109241"	USPAT;	2003/06/04 09:18
	[US-PGPUB;	
	1		EPO; JPO;	İ
14	2	#20020:14144#	DERWENT	
T.1	[2]	"20020114144"	USPAT;	2003/06/04 09:18
	1		US-PGPUB;	
			EPO; JPO;	
15	24	E450000 5450000	DERWENT	
10	24	5450283.pn 5450283.pn. 5784261.pn.	USPAT;	2003/06/04 09:18
		5895229.pn. 5981314.pn. 5998243.pn.	US-PGPUB;	
		6038136.pn. 6049122.pn. 6071755.pn.	EPO; JPO;	
	 	6081997.pn. 6344162.pn. "20020109241" "20020114144"	DERWENT	
		20020114144"	<u>_</u>	